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May 2014

FCA16N60N

N-Channel SupreMOS[®] MOSFET

600 V, 16 A, 199 mΩ

Features

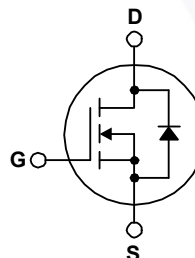
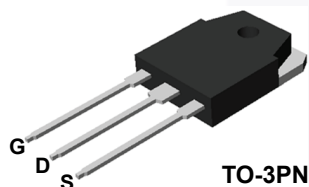
- $R_{DS(on)} = 170 \text{ m}\Omega$ (Typ.) @ $V_{GS} = 10\text{V}$, $I_D = 8 \text{ A}$
- Ultra Low Gate Charge (Typ. $Q_g = 40.2 \text{ nC}$)
- Low Effective Output Capacitance (Typ. $C_{oss(eff.)} = 176 \text{ pF}$)
- 100% Avalanche Tested
- RoHS Compliant

Application

- PDP TV
- AC-DC Power Supply

Description

The SupreMOS[®] MOSFET is Fairchild Semiconductor's next generation of high voltage super-junction (SJ) technology employing a deep trench filling process that differentiates it from the conventional SJ MOSFETs. This advanced technology and precise process control provides lowest R_{sp} on-resistance, superior switching performance and ruggedness. SupreMOS MOSFET is suitable for high frequency switching power converter applications such as PFC, server/telecom power, FPD TV power, ATX power, and industrial power applications.



MOSFET Maximum Ratings $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter		FCA16N60N	Unit
V _{DSS}	Drain to Source Voltage		600	V
V _{GSS}	Gate to Source Voltage		±30	V
I _D	Drain Current	- Continuous (T _C = 25°C)	16.0	A
		- Continuous (T _C = 100°C)	10.1	
I _{DM}	Drain Current	- Pulsed (Note 1)	48.0	A
E _{AS}	Single Pulsed Avalanche Energy (Note 2)		355	mJ
I _{AR}	Avalanche Current (Note 1)		5.3	A
E _{AR}	Repetitive Avalanche Energy (Note 1)		1.34	mJ
dv/dt	MOSFET dv/dt		100	V/ns
	Peak Diode Recovery dv/dt (Note 3)		20	V/ns
P _D	Power Dissipation	(T _C = 25°C)	134.4	W
		- Derate Above 25°C	1.08	W/°C
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C
T _I	Maximum Lead Temperature for Soldering, 1/8" from Case for 5 Seconds		300	°C

Thermal Characteristics

Symbol	Parameter	FCA16N60N	Unit
$R_{\theta JC}$	Thermal Resistance, Junction to Case, Max.	0.93	$^\circ\text{C/W}$
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient, Max.	40	

Package Marking and Ordering Information

Part Number	Top Mark	Package	Packing Method	Reel Size	Tape Width	Quantity
FCA16N60N	FCA16N60N	TO-3PN	Tube	N/A	N/A	30 units

Electrical Characteristics $T_C = 25^\circ\text{C}$ unless otherwise noted.

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
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Off Characteristics

BV_{DSS}	Drain to Source Breakdown Voltage	$I_D = 1\text{ mA}$, $V_{GS} = 0\text{ V}$, $T_C = 25^\circ\text{C}$	600	-	-	V
$\Delta BV_{DSS} / \Delta T_J$	Breakdown Voltage Temperature Coefficient	$I_D = 1\text{ mA}$, Referenced to 25°C	-	0.73	-	$V/^\circ\text{C}$
I_{DSS}	Zero Gate Voltage Drain Current	$V_{DS} = 480\text{ V}$, $V_{GS} = 0\text{ V}$	-	-	10	μA
		$V_{DS} = 480\text{ V}$, $V_{GS} = 0\text{ V}$, $T_C = 125^\circ\text{C}$	-	-	100	
I_{GSS}	Gate to Body Leakage Current	$V_{GS} = \pm 30\text{ V}$, $V_{DS} = 0\text{ V}$	-	-	± 100	nA

On Characteristics

$V_{GS(th)}$	Gate Threshold Voltage	$V_{GS} = V_{DS}$, $I_D = 250\text{ }\mu\text{A}$	2.0	-	4.0	V
$R_{DS(on)}$	Static Drain to Source On Resistance	$V_{GS} = 10\text{ V}$, $I_D = 8\text{ A}$	-	0.170	0.199	Ω
g_{FS}	Forward Transconductance	$V_{DS} = 40\text{ V}$, $I_D = 8\text{ A}$	-	20	-	S

Dynamic Characteristics

C_{iss}	Input Capacitance	$V_{DS} = 100\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	1630	2170	pF
C_{oss}	Output Capacitance		-	70	95	pF
C_{rss}	Reverse Transfer Capacitance		-	5	10	pF
C_{oss}	Output Capacitance	$V_{DS} = 380\text{ V}$, $V_{GS} = 0\text{ V}$, $f = 1\text{ MHz}$	-	40	60	pF
$C_{oss(eff.)}$	Effective Output Capacitance	$V_{DS} = 0\text{ V}$ to 480 V , $V_{GS} = 0\text{ V}$	-	176	-	pF
$Q_{g(tot)}$	Total Gate Charge at 10V	$V_{DS} = 380\text{ V}$, $I_D = 8\text{ A}$, $V_{GS} = 10\text{ V}$ (Note 4)	-	40.2	52.3	nC
Q_{gs}	Gate to Source Gate Charge		-	6.7	-	nC
Q_{gd}	Gate to Drain "Miller" Charge		-	12.9	-	nC
ESR	Equivalent Series Resistance (G-S)	$f = 1\text{ MHz}$	-	2.9	-	Ω

Switching Characteristics

$t_{d(on)}$	Turn-On Delay Time	$V_{DD} = 380\text{ V}$, $I_D = 8\text{ A}$, $V_{GS} = 10\text{ V}$, $R_G = 4.7\text{ }\Omega$ (Note 4)	-	15.8	41.6	ns
t_r	Turn-On Rise Time		-	15.5	41.0	ns
$t_{d(off)}$	Turn-Off Delay Time		-	60.3	130.6	ns
t_f	Turn-Off Fall Time		-	20.2	50.4	ns

Drain-Source Diode Characteristics

I _S	Maximum Continuous Drain to Source Diode Forward Current	-	-	16	A	
I _{SM}	Maximum Pulsed Drain to Source Diode Forward Current	-	-	48	A	
V _{SD}	Drain to Source Diode Forward Voltage	V _{GS} = 0 V, I _{SD} = 8 A	-	-	1.2	V
t _{rr}	Reverse Recovery Time	V _{GS} = 0 V, I _{SD} = 8 A,	-	319	-	ns
Q _{rr}	Reverse Recovery Charge	di _F /dt = 100 A/μs	-	4.4	-	μC

Notes:

1. Repetitive rating; pulse-width limited by maximum junction temperature.
2. $I_{AS} = 5.3\text{ A}$, $R_G = 25\text{ }\Omega$, starting $T_J = 25^\circ\text{C}$.
3. $I_{SD} \leq 16\text{ A}$, $di/dt \leq 200\text{ A}/\mu\text{s}$, $V_{DD} = 380\text{ V}$, starting $T_J = 25^\circ\text{C}$.
4. Essentially independent of operating temperature typical characteristics.

Typical Performance Characteristics

Figure 1. On-Region Characteristics

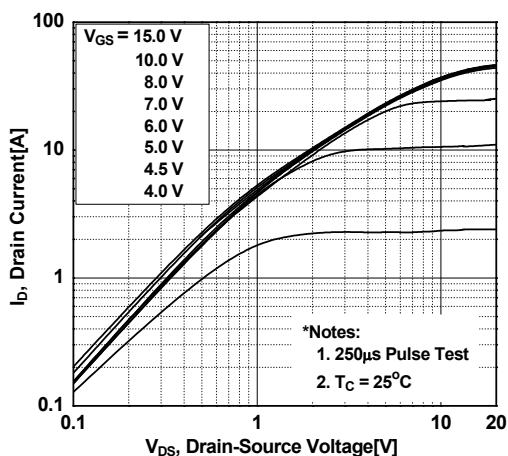


Figure 2. Transfer Characteristics

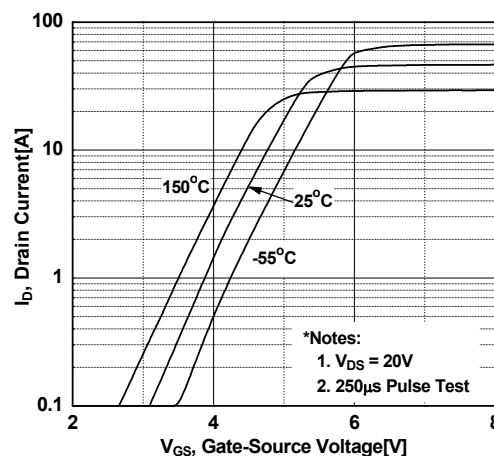


Figure 3. On-Resistance Variation vs. Drain Current and Gate Voltage

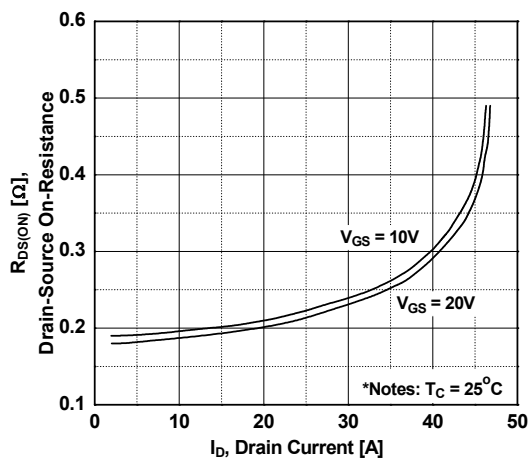


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

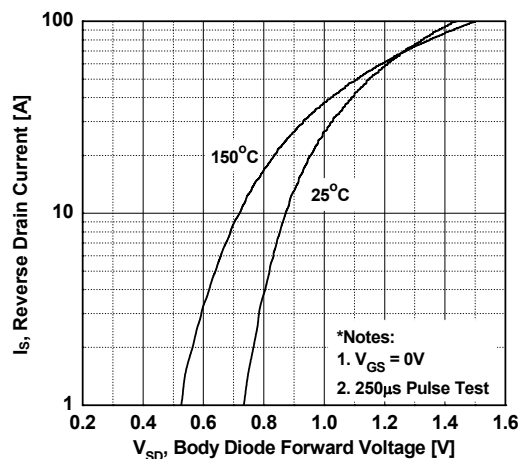


Figure 5. Capacitance Characteristics

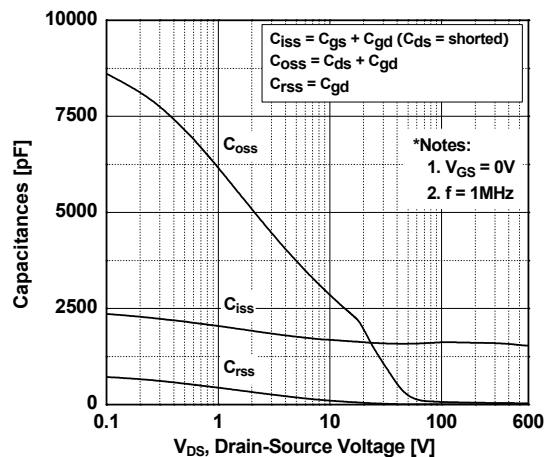
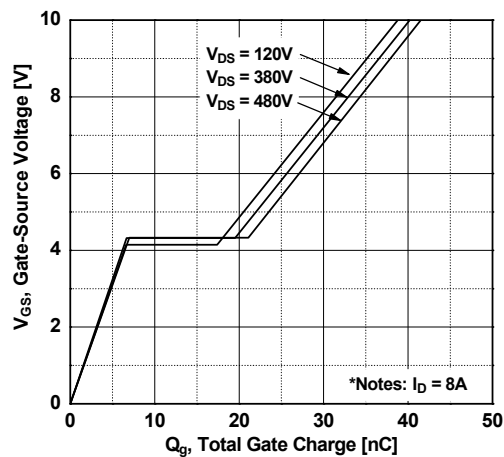


Figure 6. Gate Charge Characteristics



Typical Performance Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

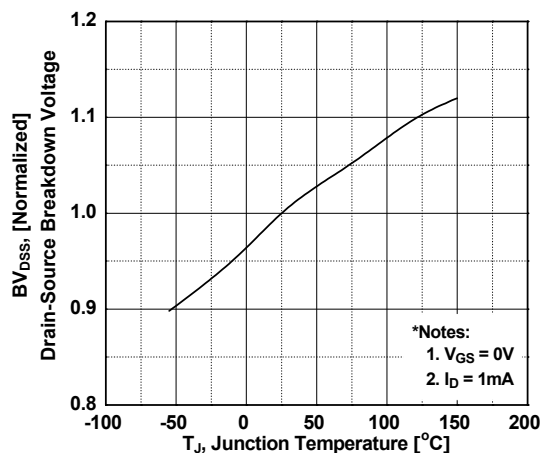


Figure 8. On-Resistance Variation vs. Temperature

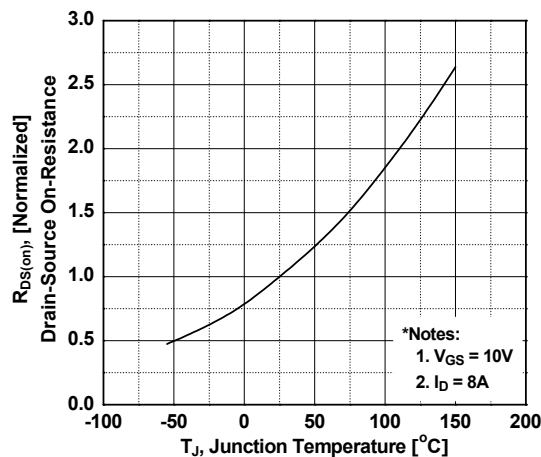


Figure 9. Maximum Safe Operating Area

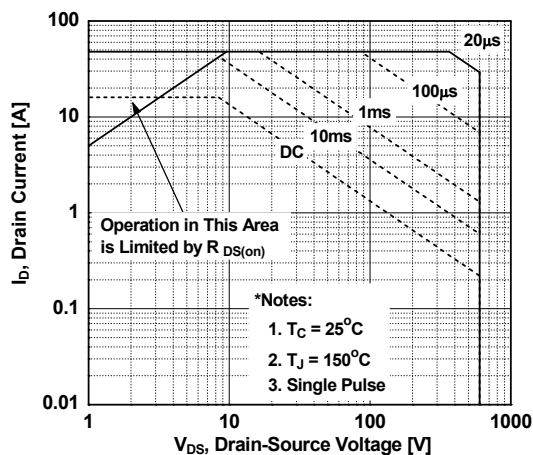


Figure 10. Maximum Drain Current vs. Case Temperature

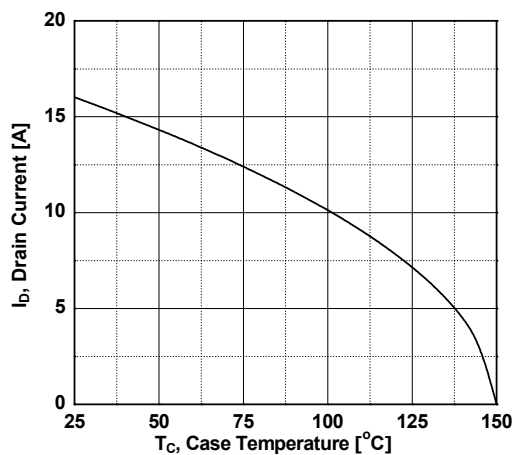
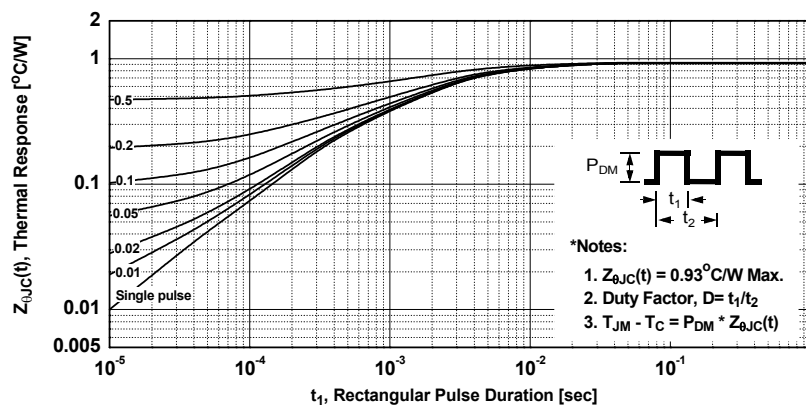


Figure 11. Transient Thermal Response Curve



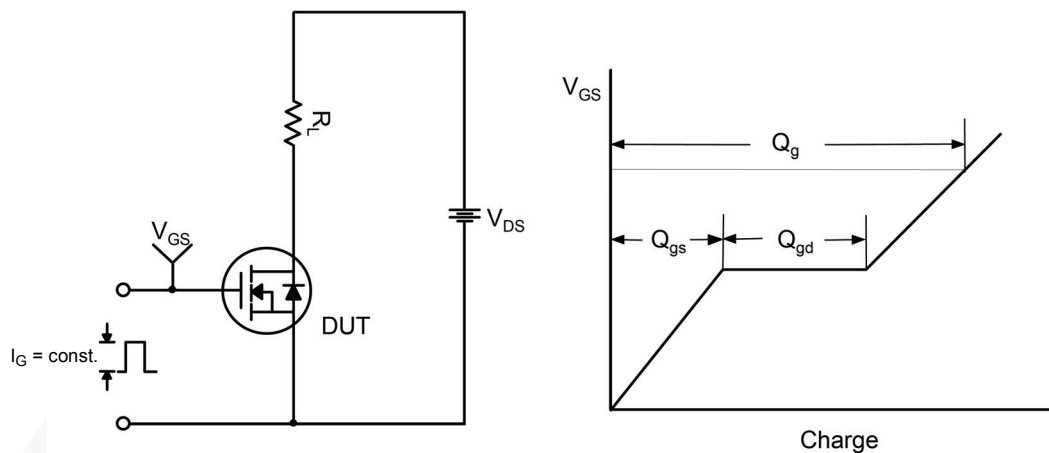


Figure 12. Gate Charge Test Circuit & Waveform

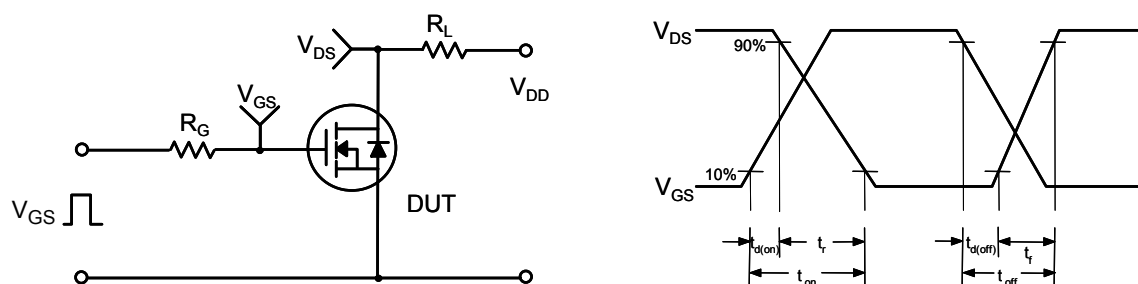


Figure 13. Resistive Switching Test Circuit & Waveforms

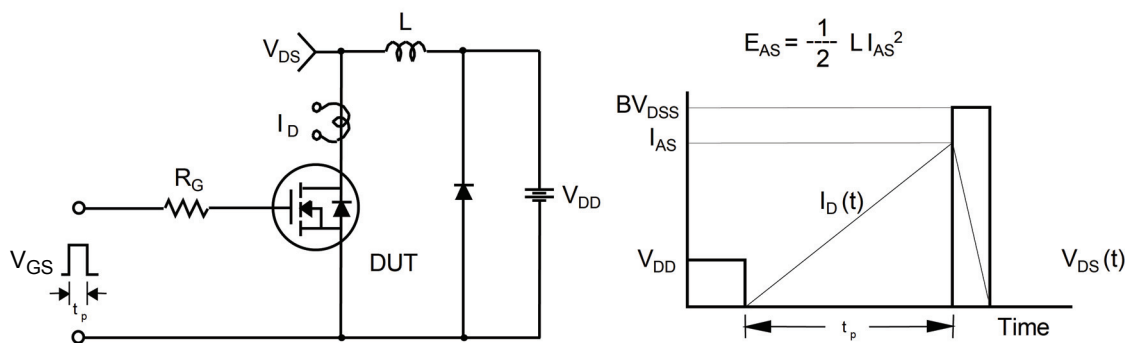
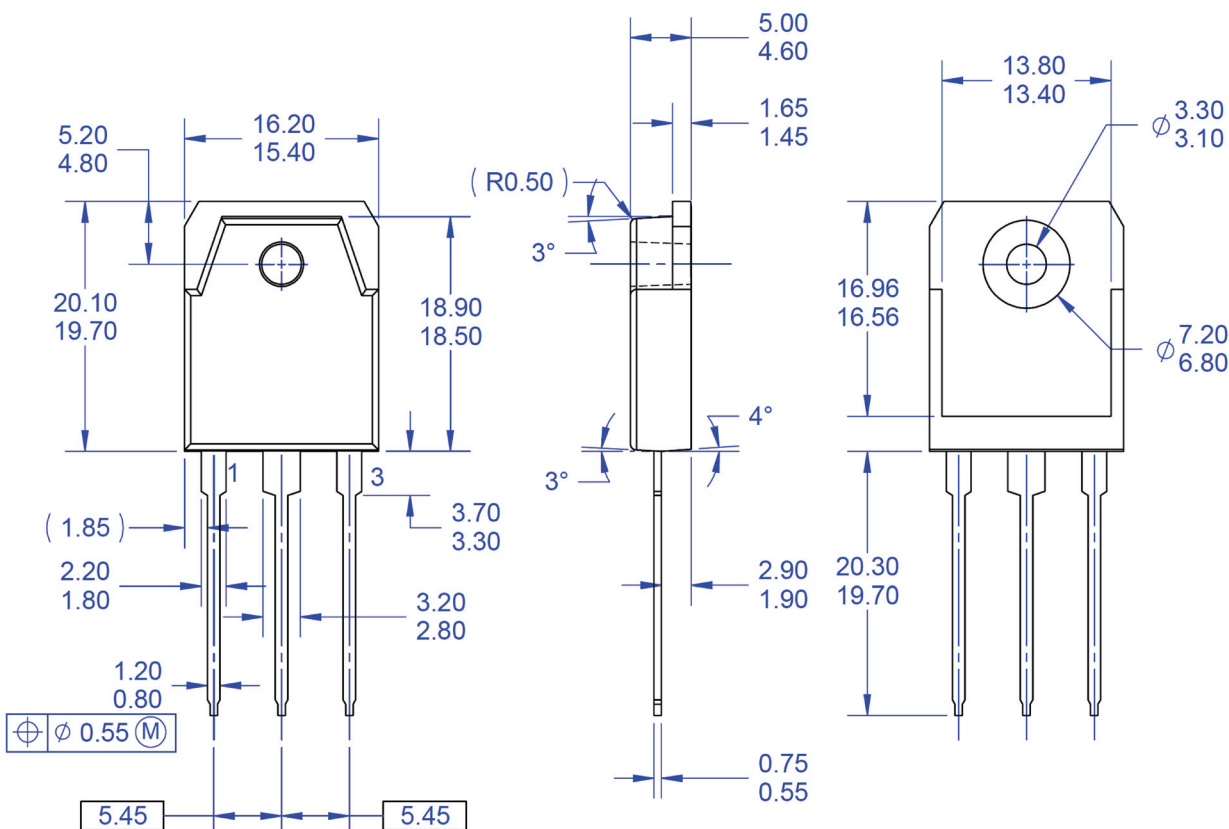


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms



Figure 15. Peak Diode Recovery dv/dt Test Circuit & Waveforms

Mechanical Dimensions



NOTES: UNLESS OTHERWISE SPECIFIED

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Figure 16. TO3PN, 3-Lead, Plastic, EIAJ SC-65

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